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AN 127:22028 HCA

TI Copper alloys for electronic apparatus and their manufacture

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SO Jpn. Kokai Tokkyo Koho, 9 pp.

CODEN: JKXXAF

DT Patent

LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 09078162	A2	19970325	JP 1996-2768	19960111
PRAI	JP 1995-173700		19950710		
AB	The title Cu alloys contain Cr 0.1-0.4, Sn 0.05-2, Zn 0.05-2, Pb and/or Ca total 0.005-0.2, P < 0.01, S < 0.005 and O <sub>2</sub> < 0.005%; size of crystd. or pptd. substances < 3 .mu.m, and grain size < 5 .mu.m. Optionally, the Cu alloys may also contain Zr 0.01-0.2%. The Cu alloys for electronic app. are manufd. by casting the above stated Cu alloys at cooling speed .gtoreq. 5.degree./s, hot working at 850-1000.degree., cooling at cooling speed .gtoreq. 10.degree./s, cold working at draft .gtoreq. 80%, heat treating at 400-500.degree. for 10 min to 24 h, cold working at draft .ltoreq. 50%, and final heat treating at 300-600.degree. for 10 min to 12 h in order. The Cu alloys have good strength, elec. cond., solderability, and punchability.				